

<b>PCN Number:</b>	20140421002		<b>PCN Date:</b>	04/23/2014	
<b>Title:</b>	Qualification of TI Clark as an Alternate Assembly site and material set change for the ADS42JB/LBXX Device family				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Phone:</b>	+1(214)480-6037	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	07/23/2014	<b>Estimated Sample Availability:</b>	Date provided upon request		
<b>Change Type:</b>					
<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
	<input type="checkbox"/>		Part number change		
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments is pleased to announce the qualification of CLARK AT as an additional assembly site for the ADS42JB/LBXX Device family. Cu bond wire will be introduced into Clark. The material set differences are noted below:					
		<b>UTAC</b>	<b>Clark-AT</b>		
<b>Mount Compound</b>		SID#PZ0031	<b>4207123</b>		
<b>Bond Wire/Diameter</b>		Au, 1.0 mil	<b>Cu, 0.8 mil</b>		
<b>Reason for Change:</b>					
Continuity of Supply					
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>					
None					
<b>Changes to product identification resulting from this PCN:</b>					
Assembly Site					
UTAC		Assembly Site Origin (22L)		ASO: NSE	
<b>CLARK-AT</b>		Assembly Site Origin (22L)		ASO: <b>QAB</b>	
Sample product shipping label (not actual product label)					
 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2Q:		 Pb G4			
MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04		(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS		ITEM: 39 LBL: 5A (L)T0:1750	
<b>Topside Device marking:</b>					
Assembly site code for NSE= J					
Assembly site code for QAB= I					

Product Affected			
ADS42JB46IRGC25	ADS42JB49IRGCR	ADS42JB69IRGCT	ADS42LB69IRGC25
ADS42JB46IRGCR	ADS42JB49IRGCT	ADS42LB49IRGC25	ADS42LB69IRGCR
ADS42JB46IRGCT	ADS42JB69IRGC25	ADS42LB49IRGCR	ADS42LB69IRGCT
ADS42JB49IRGC25	ADS42JB69IRGCR	ADS42LB49IRGCT	

Qualification Data – Approved April, 2014			
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.			
Reference Qualification# 2 : ADS42JB69 (MSL 3-260C)			
Package Construction Details			
Assembly Site:	Clark-AT	Mold Compound:	4208625
# Pins-Designator, Family:	64-RGC, VQFN	Mount Compound:	4207123
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.8 Mil Dia., Cu
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			
Reliability Test	Conditions	Sample Size/Fail	
Electrical Characterization	Per Datasheet Parameters	Pass	
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	
Notes ** - Preconditioning sequence: Level 3-260C.			

Qualification Data – Approved October, 2013				
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Reference Qualification: DAC5682ZIRGCR (MSL 3-260C)				
Package Construction Details				
Assembly Site:	CLARK AT	Mold Compound:	4208625	
# Pins-Designator, Family:	64-RGC, WSON	Mount Compound:	4207768	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.80 mil Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
Electrical Characterization	side by side	pass	pass	pass
**High Temp. Storage Bake	170C (420 hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 ATM (96 hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
ESD CDM	+/- 500V	pass	pass	pass
Notes ** - Preconditioning sequence: Level 3-260C.				

## Qualification Data – Approved October, 2012

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

### Reference Qualification# 2 : VSP5324RGC (MSL 3-260C)

#### Package Construction Details

Assembly Site:	Clark-AT	Mold Compound:	4208625
# Pins-Designator, Family:	64-RGC, VQFN	Mount Compound:	4207123
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.8 Mil Dia., Cu

**Qualification:**     Plan     **Test Results**

Reliability Test	Conditions	Sample Size/Fail
Electrical Characterization	Per Datasheet Parameters	pass
**Autoclave 121C	121C, 2 ATM (96 hrs)	77/0
ESD HBM	+/- 500V, 1000V	pass
ESD CDM	+/- 250V	pass
Latch-up	( per JESD78 )	pass
Ball Bond Shear	76 balls, 3 units min	pass
Bond Pull	76 Wire, 3 units min	pass

Notes    \*\*- Preconditioning sequence: Level 3-260C.

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>